

Product Change Notification - LIAL-08TVGL467

Date:

19 Jul 2018

Product Category:

8-bit PIC Microcontrollers; 16-Bit - Microcontrollers and Digital Signal Controllers; USB Bridge; USB Power Delivery

Affected CPNs:

7

Notification subject:

CCB 3262, 3262.001-3262.003 Final Notice: Qualification of CuPdAu wire in selected products of the 200K wafer technology available in different QFN packages at MTAI assembly site.

Notification text:

PCN Status:

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 28L QFN-S (6x6mm), 28L QFN (6x6mm), 20L QFN (5x5mm), 16L QFN (4x4mm), 20L QFN (4x4mm) and 16L QFN (3x3mm) packages at MTAI assembly site.

Pre Change:

Assembled at MTAI using gold (Au) bond wire, 3280 die attach, G700LTD molding compound and A194 lead frame material or assembled at NSEB using gold (Au) bond wire, 8200T die attach, G770HCD molding compound and C194 or EFTEC-64T lead frame material

Post Change:

Assembled at MTAI using palladium coated copper with gold flash (CuPdAu) bond wire, 3280 die attach, G700LTD molding compound and A194 lead frame material

Pre and Post Change Summary:

	Pre C	Post Change			
Assembly Site	Microchip Technology Thailand HQ (MTAI)	UTAC Thai Limited (UTL-1) LTD. (NSEB)	Microchip Technology Thailand HQ (MTAI)		
Wire material	Au	Au	CuPdAu		
Die attach material	3280	8200T	3280		
Molding compound material	G700LTD	G770HCD	G700LTD		
Lead frame material	A194	C194/ EFTEC-64T	A194		

Impacts to Data Sheet: None Change Impact: None Reason for Change:



To improve on-time delivery performance by qualifying palladium coated copper with gold flash (CuPdAu) bond wire

Change Implementation Status:

In Progress

Estimated First Ship Date:

June 22, 2018(date code: 1825)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	March 2018			>	May 2018				June 2018						
Workweek	09	10	11	12	13	>	18	19	20	21	22	23	24	25	26
Initial PCN Issue Date					Х										
Qual Report										V					
Availability										^					
Final PCN Issue Date										Х					
Estimated														Х	
Implementation Date														^	

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

March 27, 2018: Issued initial notification.

April 02, 2018: Re-issued initial notification to correct the time table summary

May 22, 2018: Issued final notification. Attached is the qualification report. Provided estimated first ship date to be on June 22, 2018.

July 19, 2018: Re-issued final notification to include NSEB assembly site in the pre-change. Update Affected CPN list.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_LIAL-08TVGL467_QUAL_REPORT.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PIC18F14K22T-E/MLVAO PIC18F24K20T-E/MLVAO PIC18F24K22T-E/MLVAO PIC18F25K20-I/MLVAO PIC18F25K20T-E/MLVAO MCP2200-I/MQVAO MCP2200T-E/MQVAO MCP2200T-I/MQVAO PIC16F1503-E/MGVAO PIC16F1503-I/MGVAO PIC16F1503T-E/MGVAO PIC16F1503T-I/MGVAO PIC16F1508-E/MLVAO PIC16F1508T-E/MLVAO PIC16F1508T-I/MLVAO PIC16F1509-E/MLVAO PIC16F1509T-E/MLVAO PIC16F1509T-I/MLVAO PIC16F1704-E/MLVAO PIC16F1704-I/MLVAO PIC16F1704T-E/MLVAO PIC24F16KA102T-I/MLVAO PIC24FV16KA302-I/MLVAO PIC24FV16KA302T-I/MLVAO UTC2000-E/MG042 UTC2000T-E/MG042 PIC16F1704T-I/MLVAO PIC16F1705-I/MLVAO PIC16F1705T-I/MLVAO PIC16F1718-I/MLVAO PIC16F1718T-I/MLVAO PIC16F1764T-E/MLVAO PIC16F1783T-E/MLVAO PIC16F1786-E/MLVAO PIC16F1786-I/MLVAO PIC16F1786T-E/MLVAO PIC16F1786T-I/MLVAO PIC16F1788-E/MLVAO PIC16F1788-I/MLVAO PIC16F1788T-E/MLVAO PIC16F1788T-I/MLVAO PIC16F1823-E/MLVAO PIC16F1823-I/MLVAO PIC16F1823T-E/MLVAO PIC16F1823T-I/MLVAO PIC16F1824-E/MLVAO

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PIC16F1824-I/MLVAO PIC16F1824T-E/MLVAO PIC16F1824T-I/MLVAO PIC16F1825-E/MLVAO PIC16F1825-I/MLVAO PIC16F1825T-E/MLVAO PIC16F1825T-I/MLVAO PIC16F1827-I/MLVAO PIC16F1827T-I/MLVAO PIC16F1828-E/MLVAO PIC16F1828-I/MLVAO PIC16F1828T-E/MLVAO PIC16F1828T-I/MLVAO PIC16F1829-E/MLVAO PIC16F1829-I/MLVAO PIC16F1829T-E/MLVAO PIC16F1829T-I/MLVAO PIC16F1938-E/MLVAO PIC16F1938T-E/MLVAO PIC16F1938T-I/MLVAO PIC16LF1454-I/MLVAO PIC16LF1454T-I/MLVAO PIC16LF1554-E/MLVAO PIC16LF1554-I/MLVAO PIC16LF1554T-E/MLVAO PIC16LF1554T-I/MLVAO PIC16LF1559T-E/MLVAO PIC16LF1559T-I/MLVAO PIC16LF1828-I/MLVAO PIC16LF1828T-E/MLVAO PIC16LF1828T-I/MLVAO PIC16LF1829-E/MLVAO PIC16LF1829-I/MLVAO PIC16LF1829T-E/MLVAO PIC16LF1829T-I/MLVAO PIC16LF1936-E/MLVAO PIC16LF1936T-E/MLVAO PIC16LF1938-I/MLVAO PIC16LF1938T-I/MLVAO PIC18F14K22-E/MLVAO PIC18F25K20T-I/MLVAO PIC18F25K22-E/MLVAO PIC18F25K22T-E/MLVAO PIC18F25K80-E/MMVAO PIC18F25K80-I/MMVAO PIC18F25K80T-E/MMVAO PIC18F25K80T-I/MMVAO PIC18F26K20-I/MLVAO PIC18F26K20T-I/MLVAO

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PIC18F26K22T-E/MLVAO PIC18F26K80-E/MMVAO PIC18F26K80T-E/MMVAO PIC18F26K80T-I/MMVAO PIC18LF26K22T-E/MLVAO PIC24F16KA102-E/MLVAO